

### **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitance load, derate current by 20%.

Characteristic	Symbol	MURS140	MURS160	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage (Note 10)	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	400	600	٧
RMS Reverse Voltage	V <sub>R(RMS)</sub>	283	424	V
Average Rectified Output Current @ T <sub>T</sub> = +135°C	lo	1	.0	Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	3	35	Α

### **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Terminal (Note 6)	$R_{\theta JT}$	15	°C/W
Operating Temperature Range	$T_J$	-55 to +150	°C
Storage Temperature Range	T <sub>STG</sub>	-55 to +175	°C

# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Forward Voltage	@ I <sub>F</sub> = 1.0A, T <sub>J</sub> = +25°C @ I <sub>F</sub> = 1.0A, T <sub>J</sub> = +150°C		1.25 1.05	V
Peak Reverse Current at Rated DC Blocking Voltage (Note 10)	@ T <sub>A</sub> = +25°C @ T <sub>A</sub> = +150°C	IDA4	5.0 150	μΑ
Reverse Recovery Time (Note 8)		t <sub>rr</sub>	50	ns
Forward Recovery Time (Note 9)		t <sub>fr</sub>	50	ns
Typical Total Capacitance (Note 7)		Ст	10	pF

Notes:

- 6. Unit mounted on PC board with 5.0 mm<sup>2</sup> (0.013 mm thick) copper pads as heat sink.

- 8. Unit mounted on PC board with 3.0 mm (0.013 mm trick) copp. 7. Measured at 1.0MHz and applied reverse voltage of 4V DC. 8. Measured with  $I_F = 0.5A$ ,  $I_R = 1.0A$ ,  $I_{rr} = 0.25A$ . See Figure 5. 9. Measured with  $I_F = 1.0A$ , di/dt =  $100A/\mu s$ , Duty Cycle  $\leq 2.0\%$ . 10. Short duration pulse test used to minimize self-heating effect.



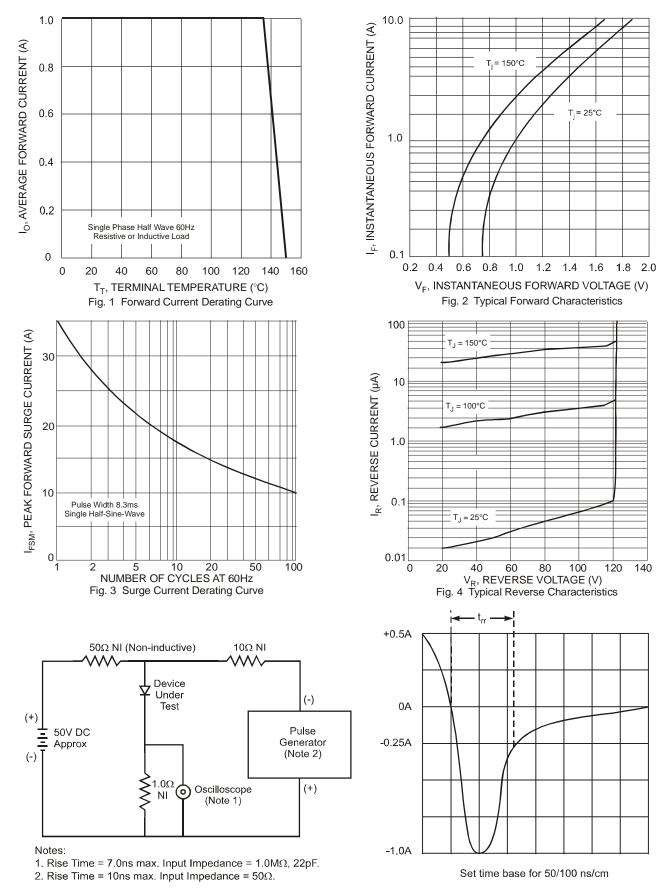
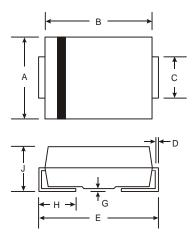


Fig. 5 Reverse Recovery Time Characteristic and Test Circuit



# **Package Outline Dimensions**

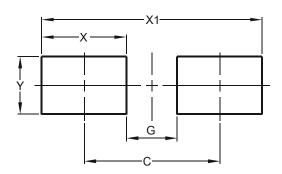
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SMB		
Dim	Min	Max
Α	3.30	3.94
В	4.06	4.57
С	1.96	2.21
D	0.15	0.31
Е	5.00	5.59
G	0.05	0.20
Н	0.76	1.52
7	2.00	2.50
All Dimensions in mm		

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	4.30
G	1.80
Х	2.50
X1	6.80
Υ	2.30



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